

# P-Channel 8 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)	
- 8	$0.122$ at $V_{GS} = -4.5 \text{ V}$	1.2		
	0.141 at V <sub>GS</sub> = - 2.5 V	1.1	5.91	
	0.168 at V <sub>GS</sub> = - 1.8 V	0.60	5.91	
	0.198 at V <sub>GS</sub> = - 1.5 V	0.50		

#### **FEATURES**

 Halogen-free According to IEC 61249-2-21 Definition

Compliant to RoHS Directive 2002/95/EC

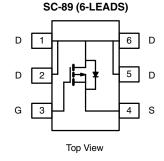
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>q</sub> Tested

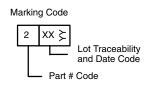


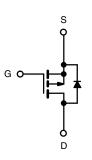
ROHS COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

• Load Switch for Portable Applications







Ordering Information: Si1051X-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	<b>S</b> (T <sub>A</sub> = 25 °C, unle	ess otherwise no	ted)	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	- 8	V
Gate-Source Voltage		V <sub>GS</sub>	± 5	V
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C	,	1.2 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C	I <sub>D</sub>	0.97 <sup>b, c</sup>	Α
Pulsed Drain Current		I <sub>DM</sub>	- 8	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	0.2 <sup>b, c</sup>	А
M ·	T <sub>A</sub> = 25 °C	D.	0.236 <sup>b, c</sup>	W
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	- P <sub>D</sub> —	0.151 <sup>b, c</sup>	
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Marrian una lumation de Ambiento d	t ≤ 5 s	- R <sub>thJA</sub>	440	530	°C/W	
Maximum Junction-to-Ambient <sup>b, d</sup>	Steady State		540	650		

#### Notes:

- a. Based on  $T_A = 25$  °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 650  $^{\circ}\text{C/W}.$

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 8			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μA		- 6.19		\//0C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 <sub>D</sub> = - 250 μΑ		2.13		mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.3		- 1	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 5 \text{ V}$			± 100	nA
Zana Cata Valtana Duain Courset	_	V <sub>DS</sub> = - 8 V, V <sub>GS</sub> = 0 V			- 1	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -8 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			- 10	μΑ
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 8			Α
_		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1.2 A		0.091	0.122	
		$V_{GS} = -2.5 \text{ V}, I_D = -1.1 \text{A}$		0.106	0.141	Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 0.60 A		0.117	0.168	
		V <sub>GS</sub> = - 1.5 V, I <sub>D</sub> = - 0.50 A		0.129	0.198	
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = - 4 V, I <sub>D</sub> = - 1.2 A		4.93		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			560		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -4 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		180		
Reverse Transfer Capacitance	C <sub>rss</sub>			112		
	0	$V_{DS} = -4 \text{ V}, V_{GS} = -5 \text{ V}, I_D = -1.2 \text{ A}$	6.3 9.4		9.45	
Total Gate Charge	$Q_g$			5.91	8.87	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = - 4 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 1.2 A		1.98		nC
Gate-Drain Charge	Q <sub>gd</sub>			1.25		
Gate Resistance	$R_g$	f = 1 MHz		9.8	14.7	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			7.2	10.8	
Rise Time	t <sub>r</sub>	$V_{DD} = -4 \text{ V, R}_{L} = 4.16 \Omega$		36	54	ns
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong$ - 0.96 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$		52	78	
Fall Time	t <sub>f</sub>			16	24	
Drain-Source Body Diode Characteris	tics					
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 8	Α
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 1.0 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			18.8	28.2	nC
Body Diode Reverse Recovery Charge Q <sub>rr</sub>		1 10 0 11/44 100 6/		4.7	7.05	
Reverse Recovery Fall Time	t <sub>a</sub>	I <sub>F</sub> = - 1.0 A, dl/dt = 100 A/μs		15		ns
Reverse Recovery Rise Time	t <sub>b</sub>			3.8		1

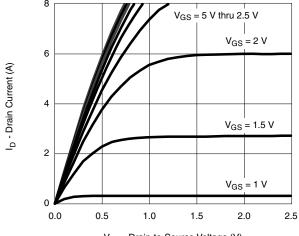
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

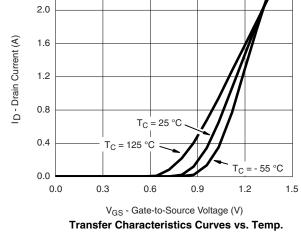
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



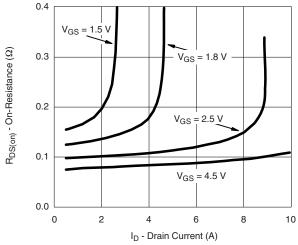
## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



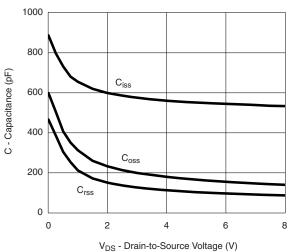
V<sub>DS</sub> - Drain-to-Source Voltage (V) **Output Characteristics** 



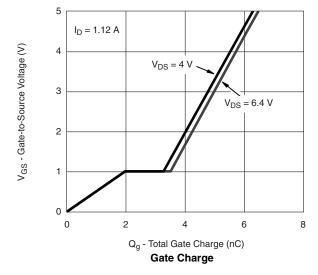
2.4

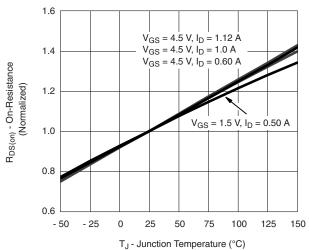


On-Resistance vs. Drain Current



Capacitance



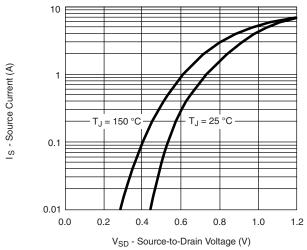


On-Resistance vs. Junction Temperature

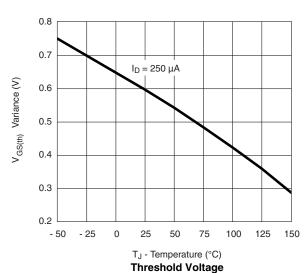
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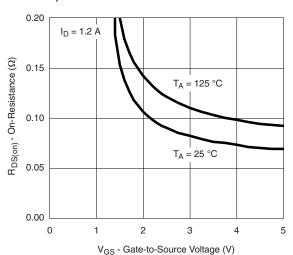
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## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)

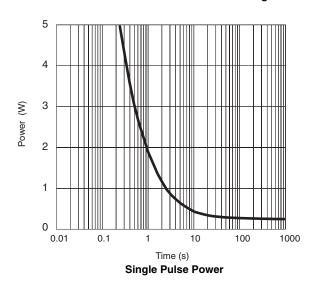


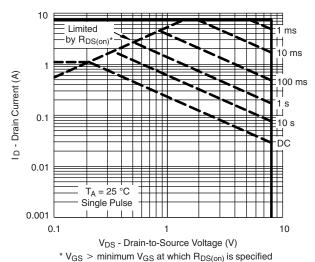
#### Source-Drain Diode Forward Voltage





On-Resistance vs. Gate-to-Source Voltage



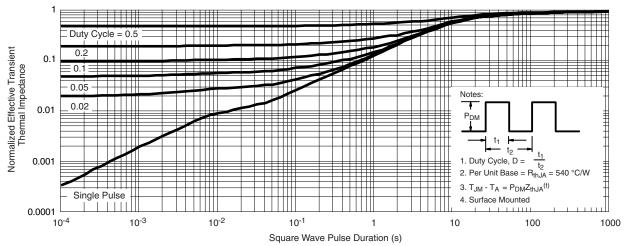


Safe Operating Area, Junction-to-Ambient





## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?74479">www.vishay.com/ppg?74479</a>.

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